Special Issue

Advanced Research on Integrated Circuits and Systems

Message from the Guest Editors

This special issue focuses on recent advances in the diverse field of Integrated Circuits and Systems (ICS). It delves into the most recent research and breakthroughs in a variety of interconnected sub-disciplines within ICS, including novel logic device architectures, emerging memory technologies, efficient power electronics design, innovative design-for-testability and design-for-manufacturing (DTCO) methodologies, and advances in electronic design automation (EDA) tools and algorithms. Contributions that investigate the interplay of these domains, particularly those that address the issues of the challenges of miniaturization, performance enhancement, power reduction, and reliability in next-generation ICS, are highly encouraged.

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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